INFORMATION DISCLOSURE CITATION

PTO-1449

ATTY. DOCKET NO.	APPLICATION NO.
P1D1C1	09/245,499
APPLICANT: Igor Y. Khandros	#25
FILING DATE: February 5, 1999	GROUP: 2841

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
KL	5,090,119	2/92	Tsuda et al.	29	843	
	3,119,172	1/64	Mazenko et al.	29	155.5	
	3,734,386	5/73	Hazel	228	5	
	2,429,222	10/4	Erhardt et al.	204	28	
	5,195,237	3/93	Cray et al.	29	838	
	4,418,857	12/83	Ainslie et al.	228	124	
	4,983,907	1/91	Crowley	324	158 F	
	5,055,780	10/91	Takagi et al.	324	158 F	
	5,187,020	2/93	Kwon et al.	428	601	

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes	Translation No
KL	4-65840	3/92	Japan	~~H01L~~	~~21/60~~		✓
	0 002 166	5/79	Europe	~~H01L~~	~~23/32~~		✓
	0 396 248	11/90	Europe	~~H01R~~	~~13/04~~		✓
	WO94/03036	3/94	PCT	~~H05K~~	~~3/36~~		✓
	DE 31 29 568	4/82	Germany	~~H01L~~	~~23/50~~		✓
	60-150657	08/85	Japan	~~257~~	~~781~~		✓

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

KL	Ando, et al., "Plating micro bonding used for Tape Carrier package", Abstracts, NIST, VLSI Packaging Workshop, October 11-13, 1993, Yorktown Heights, NY, 1 page total.
KL	"Bimetal VLSI Chip Interconnections", IBM Technical Disclosure Bulletin, April 29, 1987, No. 11, Armonk, NY USA, 2 pages total.
KL	"Corrosion Protection for Incusil Brazed Joints on Modules", IBM Technical Disclosures, Vol. 19, No. 6, p. 2059.

EXAMINER [signature] DATE CONSIDERED 3/23/01

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
KE	4,522,893	6/85	Bohlen, et al.	428	641	
	3,795,037	3/74	Luttmer	29	628	
	4,545,610	10/85	Lakritz et al.	29	589	
	5,130,779	7/92	Agarwala et al	357	67	
	5,476,211	12/95	Khandros	228	180.5	
	4,780,836	10/88	Miyazaki et al.	364	551.01	
	5,047,711	9/91	Smith et al.	324	158	

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes	Translation No
KE	0314287	6/91	Japan	~~H01L~~	~~21/60~~		✓

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER	DATE CONSIDERED
[signature]	3/23/01

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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	4,615,573	10/86	White et al.	339	17M	
	3,672,047	6/72	Sakamoto et al.	29	628	
	5,455,390	10/95	DiStefano et al.	174	262	Feb-94
	3,844,909	10/74	McCary et al.	204	40	
	3,373,481	3/68	Lins et al.	29	471.3	
	3,460,328	8/69	Christy et al.	29	481	
	3,509,270	4/70	Dube et al.	174	68.5	
	3,616,532	11/71	Beck	29	625	
	4,067,104	1/78	Tracy	29	626	
	4,295,700	10/81	Sado	339	61	
	4,330,165	5/82	Sado	339	59	
	4,532,152	7/85	Elarde	427	96	
	4,642,889	2/87	Grabbe	29	740	
	4,764,848	8/88	Simpson	361	408	
	4,777,564	10/88	Derfiny et al.	361	405	
	4,793,814	12/88	Zifcak et al.	439	66	
	4,821,148	4/89	Kobayashi et al.	361	392	
	4,860,433	8/89	Miura	29	605	
	4,893,172	1/90	Matsumoto et al.	357	79	
	4,914,814	4/90	Behum et al.	29	843	
	4,955,523	9/90	Calomagno et al.	228	179	
	4,989,069	1/91	Hawkins et al.	357	74	
	5,086,337	2/92	Noro et al.	357	74	
	5,110,032	5/92	Akiyama et al.	228	102	
	5,130,779	7/92	Agarwala et al.	357	67	
	5,366,380	11/94	Reymond	439	66	Mar-93
	5,386,344	1/95	Beaman et al.	361	785	Jan-93
	4,784,872	11/88	Mueller et al.	427	96	
	5,148,968	9/92	Schmidt et al.	228	180.2	
	4,878,611	11/89	Lo Vasco et al.	228	246	
	5,154,341	10/92	Melton et al.	228	254	

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KC	4,332,341	6/82	Minetti et al.	228	188	
	4,664,309	5/87	Allen et al.	228	563	
	5,627,406	5/97	Pace	257	700	Aug-96
	3,747,198	7/73	Benson et al.	257	784	
	3,087,239	4/63	Clagett et al.	257	784	
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	5,296,744	3/94	Liang et al.	257	784	Jun-92
	5,359,227	10/94	Liang et al.	257	784	Dec-93
	5,606,196	2/97	Lee et al.	257	503	Dec-95
	4,618,879	10/86	Mizukoshi et al.	257	784	
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	5,396,104	3/95	Kimura et al.	257	784	Nov-90
	5,639,558	6/97	Tatsumi et al.	428	458	Mar-95
	5,656,830	8/97	Zechman et al.	257	784	Oct-92
	5,091,772	2/92	Kohara et al.	257	784	
	3,519,890	7/70	Ashby	361	776	
	4,385,341	5/83	Main	361	776	
	4,728,751	3/88	Canestate	361	776	
	5,349,495	9/94	Visel et al.	361	774	Oct-90
	5,389,743	2/95	Simila et al.	174	262	
	4,996,629	2/91	Christiansen et al.	361	776	
	3,982,811	9/76	Siu et al.	439	884	
	5,298,464	3/94	Schlesinger et al.	437	216	May-92
	5,598,627	2/97	Saka et al.	29	861	Jun-95
	5,621,263	4/97	Kaida	310	333	Aug-94
	5,239,126	8/93	Oshiba	174	35R	
	3,445,770	5/69	Harmon	324	762	
	3,849,728	11/74	Evans	324	762	
	5,055,778	10/91	Okubo et al.	324	762	
	5,585,737	12/96	Shibata	324	754	Dec-94
	5,534,784	7/96	Lunn et al.	324	757	May-94
	5,506,498	4/96	Anderson et al.	324	158.1	Mar-95
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	5,220,277	6/93	Reitinger	324	158F	
	5,130,644	7/92	Ott	324	58F	
	4,961,052	10/90	Tada et al.	324	158P	
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	5,532,609	7/96	Harwood et al.	324	754	Apr-95
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	5,303,938	4/94	Miller et al.	279	3	Mar-93
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	5,214,375	5/93	Ikeuchi et al.	324	158F	Mar-92
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	4,985,676	1/91	Karasawa	324	158F	
	4,870,356	9/89	Tingley	324	158F	
	5,534,786	7/96	Kaneko et al.	324	760	Feb-95
	5,479,108	12/95	Cheng	324	765	Nov-92
	5,568,056	10/96	Ishimoto	324	754	Nov-94
	5,559,444	9/96	Farnworth et al.	324	754	May-95
	5,488,292	1/96	Tsuta	324	158.1	Oct-93
	5,410,162	4/95	Tigelaar et al.	257	048	Oct-93
	5,355,081	10/94	Nakata et al.	324	765	May-93
	5,329,228	7/94	Comeau	324	765	Jul-92
	5,140,405	8/92	King et al.	357	67	
	4,567,433	1/86	Ohkubo et al.	324	158P	
	4,697,143	9/87	Lockwood et al.	324	158P	
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	5,424,651	6/95	Green et al.	324	754	Mar-92
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KL	5,550,482	8/96	Sano	324	758	Jul-94
	5,510,724	4/96	Itoyama et al.	324	760	May-94
	5,444,366	8/95	Chiu	324	158.1	Feb-94
	5,517,126	5/96	Yamaguchi	324	758	Jul-93
	5,555,422	9/96	Nakano	324	754	Oct-95
	3,849,872	11/74	Hubacher	29	574	
	5,363,038	11/94	Love	324	158.1	Aug-92
	4,038,599	7/77	Bove et al.	324	158F	
	5,391,984	2/95	Worley	324	158.1	Nov-91
	5,444,386	8/95	Mizumura	324	754	Jan-93
	5,479,109	12/95	Lau et al.	324	758	Jan-94
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	5,601,740	2/97	Eldridge et al.	219	130	Dec-95